Tool Make & Model

ULTRATECH AP300

Tool Configuration / Specifications

1 Standard Features Target: 04/05/11
2.0 um, Extended Field, ghi-line Broadband Lens · Dual 1200 W Lamp Illuminator
Universal Size/Warped Wafer Kit: 200, and 300mm.
FOSB Cassette to Cassette Wafer Handling
Wafer Thickness Handling from 0.4 mm to 2.0 mm
PATMAX MVS Alignment System
MVS Alignment Spectrum of 530 - 570 nm
Lens Distortion Reference - No lens matching
6 Slot Reticle Stack, Manual Front Loading GEM HSMS Communications
Power Source: 208 V three phase, 5 wire, 150 amp
Environmental Chamber

2 AP300 Test Reticle 6x6

3 FOUP Wafer Handler

4 Enhanced Bottom Pellicle Protection

5 ghi-line Auto Filter Changer

6 Edge Exclusion System with one Exclusion Ring Specify ring size (15mm)

7 Closed Loop Cooling

8 Prism Purge Kit (requires CLC)

Additional Information:

- **Dual side alignment upgrade in 2006.**
- **The lens can no longer be considered a 2um lens even though it was purchased as a 2um system.**
- **Age has taken its toll on STEP400 and lens distortion has suffered.**
- **It can be considered a 4um lens now.**
- **The Dual Flip Aperture size - largest is 44mm.**

Tool is NOT a widefield system. Standard field, 44X26.7mm.

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